

Title (en)  
ELECTRONIC COMPONENT

Title (de)  
ELEKTRONISCHES BAUELEMENT

Title (fr)  
COMPOSANT ÉLECTRONIQUE

Publication  
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Application  
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Abstract (en)  
[origin: WO2010057879A1] The invention relates to an electronic component (1) comprising a conduction path structure (5) disposed on a substrate (3) and a film (7) that contacts the conduction path structure (5), wherein the film (7) has a smaller layer thickness (h) than the conduction path structure (5). The conduction path structure (5) comprises an area (11) that is covered by the film (7) for the purposes of contacting.

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